

Flip-Chip Package Analysis

Model 6 – Complete and Incompletely filled

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ME 7680

Submitted: April 9, 2021

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Introduction

This project focuses on understanding the fatigue life of solder ball in a flip-chip package. Geometry for the model has been provided and for simplicity has been modified into quarter and half for complete and incompletely filled simulations. Model 6 was assigned where only the middle and right solder balls have voids around them (see below (b)). Material properties for silicon (elastic), FR-4 (elastic), solder and underfill (strain rate dependent) were also provided. Cyclic thermal loading occurred from -40 to 125 °C for 12 cycles.

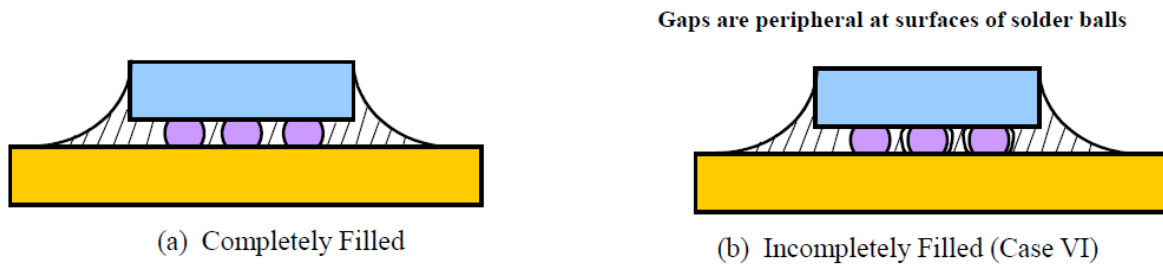


Figure 1 Model 6 Illustration

Mesh

C3D10 elements were created and each component was carefully meshed so that the nodes were connected at the mating face. Equivalence was applied to ensure consistency. Nodes were more concentrated with a finer mesh at the corner of the solder balls (red circles) as instructed. The completely filled quarter model mesh is shown below:

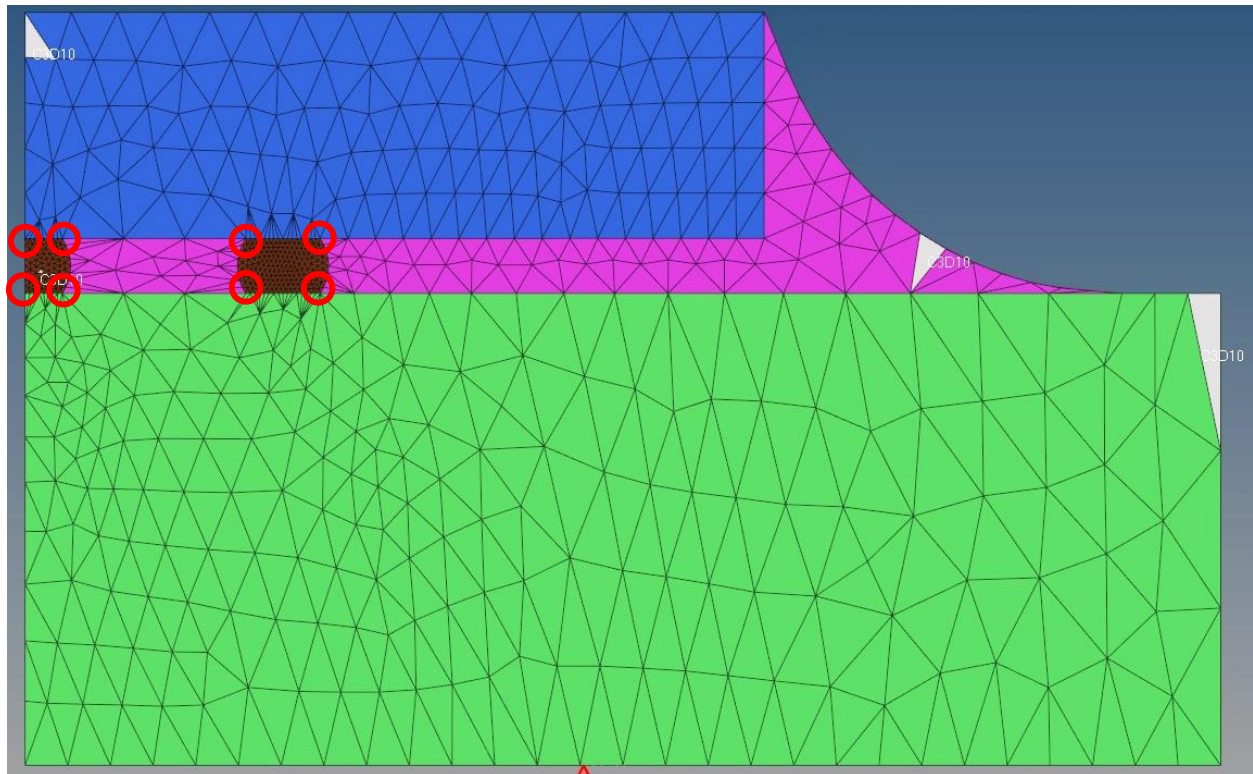


Figure 2 Meshed (connected) of Completely Filled Quarter Model

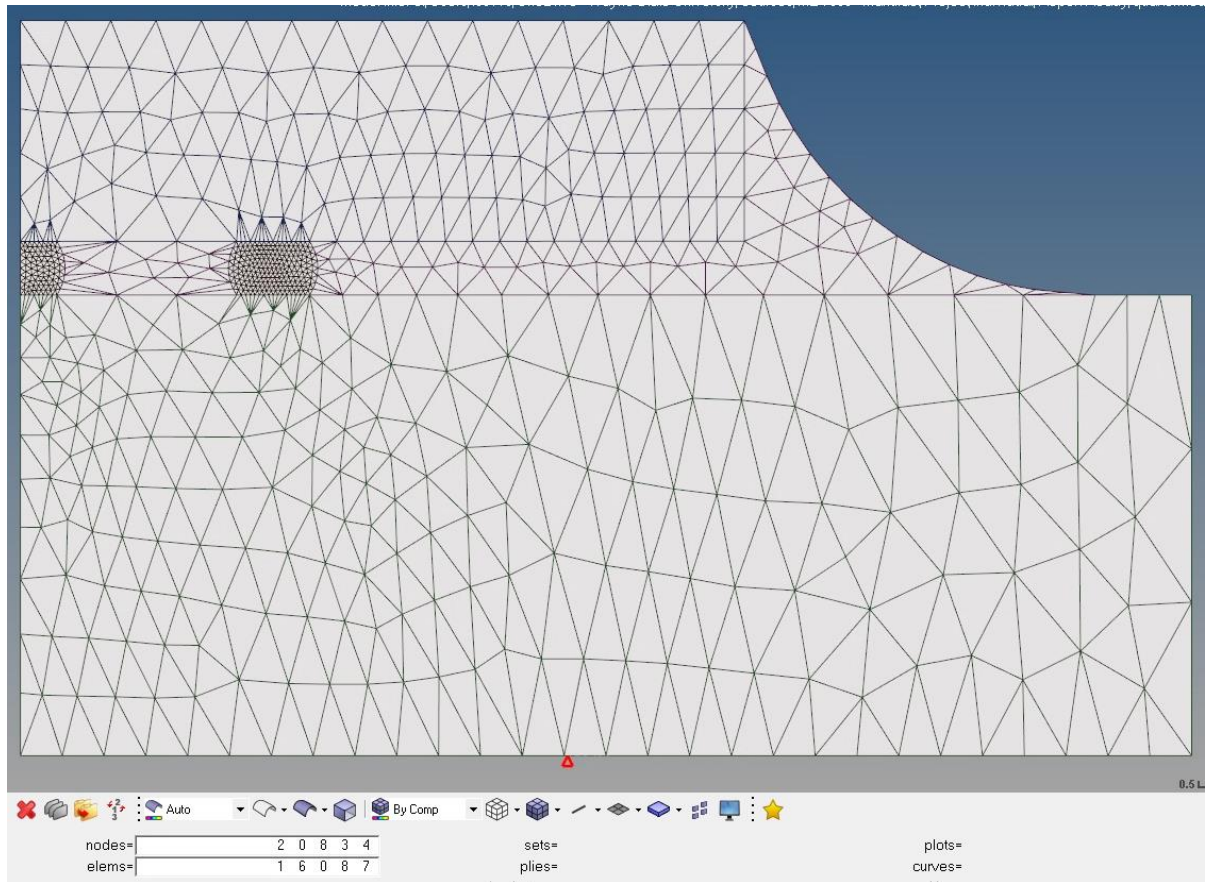


Figure 4 Nodes (20834) and elements (16087) of Completely Filled Quarter Model

The Incompletely filled half model mesh is shown below:

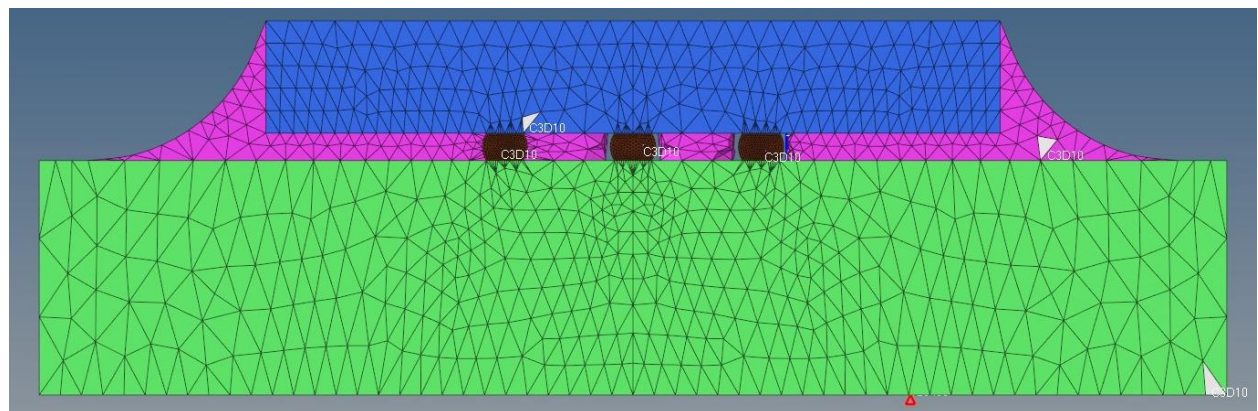


Figure 3 Meshed (connected) Incompletely Filled Half Model

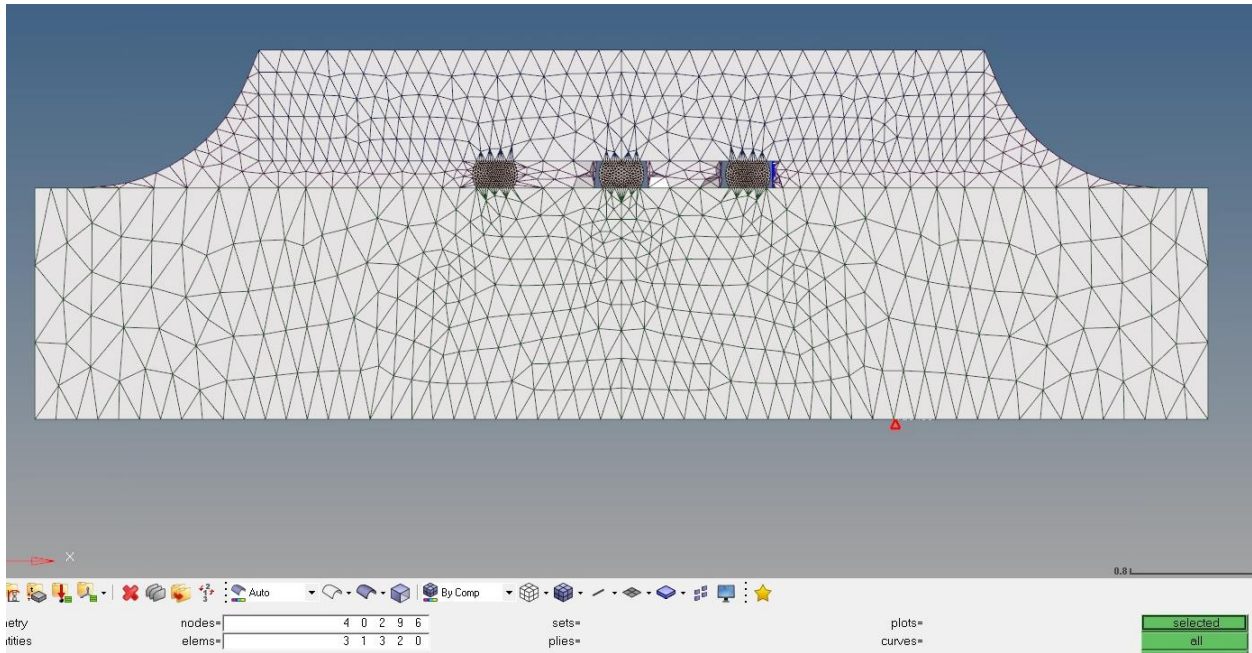


Figure 5 Nodes (40296) and Elements (31320) of Incompletely Filled Quarter Model

Boundary Conditions

The base of the flip-chip was constrained on all degrees of freedom and each node had temperature applied to it depending on the cycle. Room temperature was set at 27 C for the first initial cycle (See below).

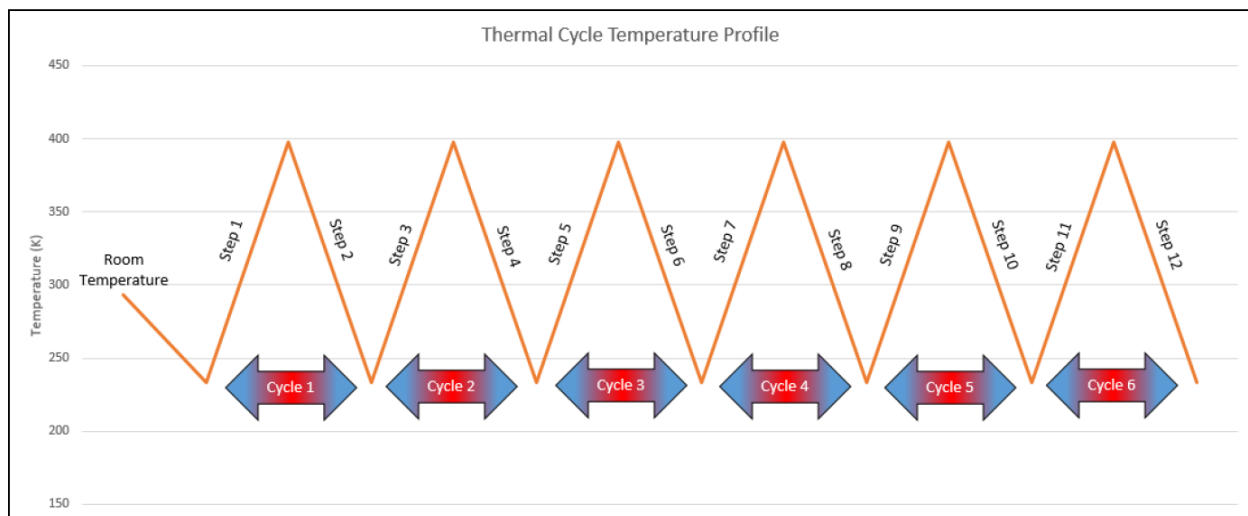
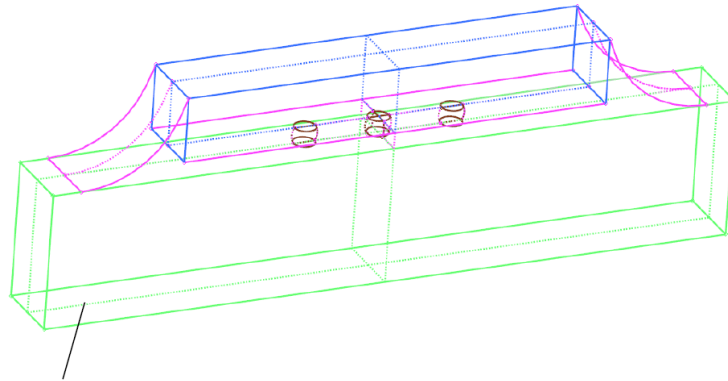


Figure 6 Illustration of 12 Cycles Ranging from -40 to 125 °C



Constrain the bottom surface

Figure 7 Boundary Constraints applied. Note the constrained surface on the bottom. Temperature constraints are applied to all nodes.

Below is an image illustrating the incompletely filled flip-chip half model constraints in Abaqus. The squares represent temperature, and the bottom surface can be seen with constraints on all degrees of freedom.

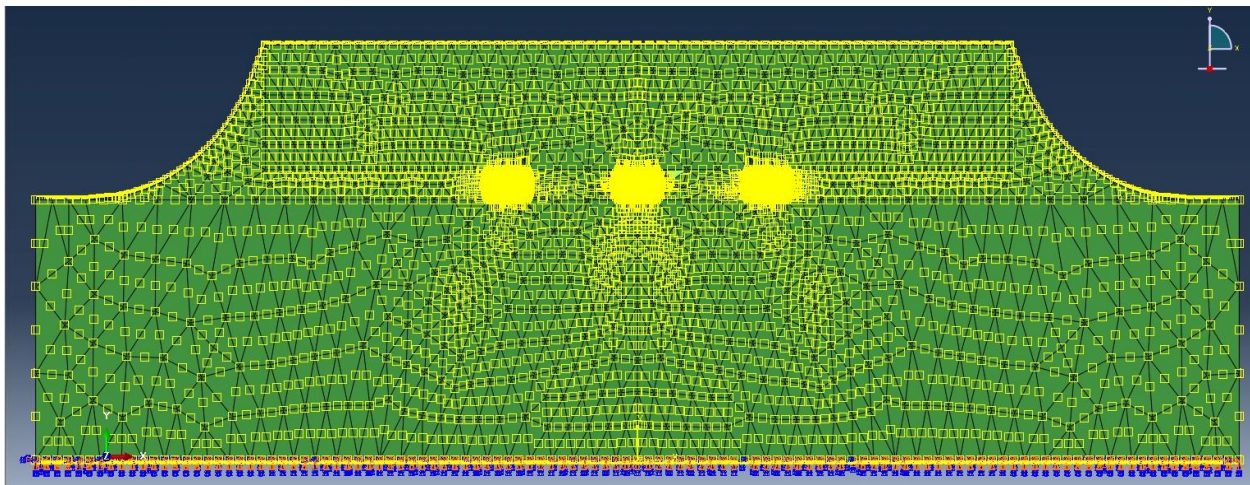


Figure 8 Illustration of Boundary Conditions in Abaqus. Squares are temperatures and the bottom surfaces are constraints on all degrees of freedom.

Results

Fatigue Life Equation (Coffin-Manson):

$$(N_f)^\beta \Delta\gamma^p = C^p$$

$$C^p = 1.14 \text{ and } \beta = 0.51$$

$\Delta\gamma^p$ = Applied Plastic/inelastic strain range (PEEQ)

N_f = Fatigue Life

Note: Results of $\Delta\gamma^p$ for can be seen in the tables on the next page. Below are the calculated fatigues.

Completely Filled Quarter Model:

$$(N_f)^\beta \Delta\gamma^p = C^p$$

$$(N_f)^{0.51} * 0.7206 = 1.14 = \mathbf{2.45}$$

Incompletely Filled Half Model:

$$(N_f)^\beta \Delta\gamma^p = C^p$$

$$(N_f)^{0.51} * 0.268 = 1.14 = \mathbf{17.09}$$

Table 1 Completely Filled Quarter Model Results for Max Von Mises, Principal and Equivalent Strain (PEEQ)

Model 6			Completely Filled Quarter Model					
			Max Von Mises		Max Principal		PEEQ	
			Timestep		Timestep		Timestep	
Step	Cycle	Temp (°C)	0	1	0	1	0	1
1		27	0.00	56.04	0.00	61.76	0.00	0.0023
2		-40	56.04	65.97	61.76	178.40	0.0023	0.0113
3	1	125	65.97	80.52	178.40	387.10	0.0113	0.0762
4	2	-40	80.52	72.87	387.10	229.20	0.0762	0.1330
5	3	125	72.87	74.01	229.20	328.20	0.1330	0.1922
6	4	-40	74.01	72.87	328.20	233.90	0.1922	0.2503
7	5	125	72.87	74.97	233.90	173.10	0.2503	0.3094
8	6	-40	74.97	72.90	173.10	237.30	0.3094	0.3678
9	7	125	72.90	75.31	237.30	176.00	0.3678	0.4268
10	8	-40	75.31	72.91	176.00	240.10	0.4268	0.4854
11	9	125	72.91	100.00	240.10	177.90	0.4854	0.5440
12	10	-40	100.00	72.97	177.90	242.40	0.5444	0.6030
13	11	125	72.97	100.10	242.40	179.20	0.6030	0.6620
14	12	-40	100.10	73.01	179.20	244.20	0.6620	0.7206
Last Time Step Value			73.01		244.20		0.720600	

Table 2 Incompletely Filled Half Model Results for Max Von Mises, Principal Stress and Equivalent Strain (PEEQ)

Model 6			Incompletely Filled Half Model					
			Max Von Mises		Max Principal		PEEQ	
			Timestep		Timestep		Timestep	
Step	Cycle	Temp (°C)	0	1	0	1	0	1
1		27	0.00	54.05	0.00	39.47	0.00	0.0010
2		-40	54.05	71.40	39.47	127.70	0.0010	0.0047
3	1	125	65.97	80.52	127.70	145.00	0.0047	0.0281
4	2	-40	79.64	85.96	145.00	176.30	0.0281	0.0493
5	3	125	85.96	81.11	176.30	128.30	0.0493	0.0715
6	4	-40	81.11	86.07	128.30	182.90	0.0715	0.0931
7	5	125	86.07	81.43	182.90	122.60	0.0931	0.1152
8	6	-40	81.43	86.09	122.60	185.50	0.1152	0.1370
9	7	125	86.09	81.59	185.50	119.50	0.1370	0.1590
10	8	-40	81.59	86.10	119.50	186.80	0.1590	0.1808
11	9	125	86.10	81.68	186.80	117.40	0.1808	0.2209
12	10	-40	81.68	86.12	117.40	187.40	0.2029	0.2247
13	11	125	86.12	81.75	187.40	115.90	0.2247	0.2467
14	12	-40	81.75	86.11	115.90	187.80	0.2467	0.2686
Last Time Step Value			86.11		187.80		0.268600	

Critical location for completely filled quarter model:

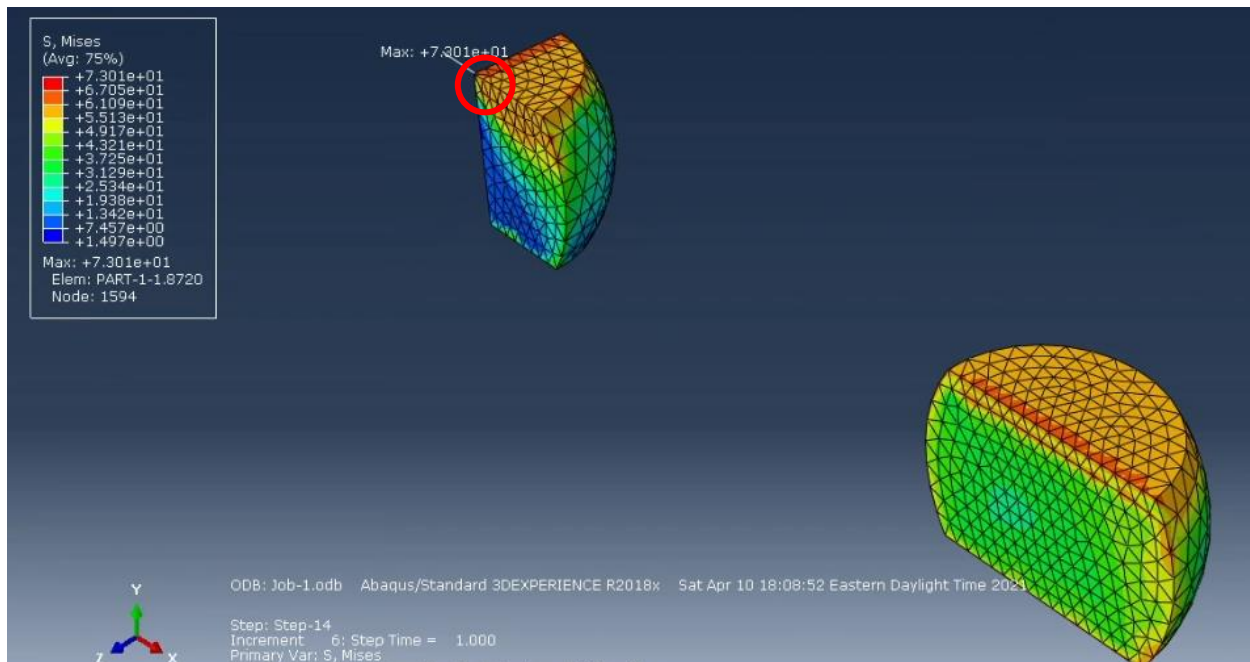


Figure 9 Complete Filled Quarter Model Critical Location (Solder)

Critical location for incompletely filled half model:

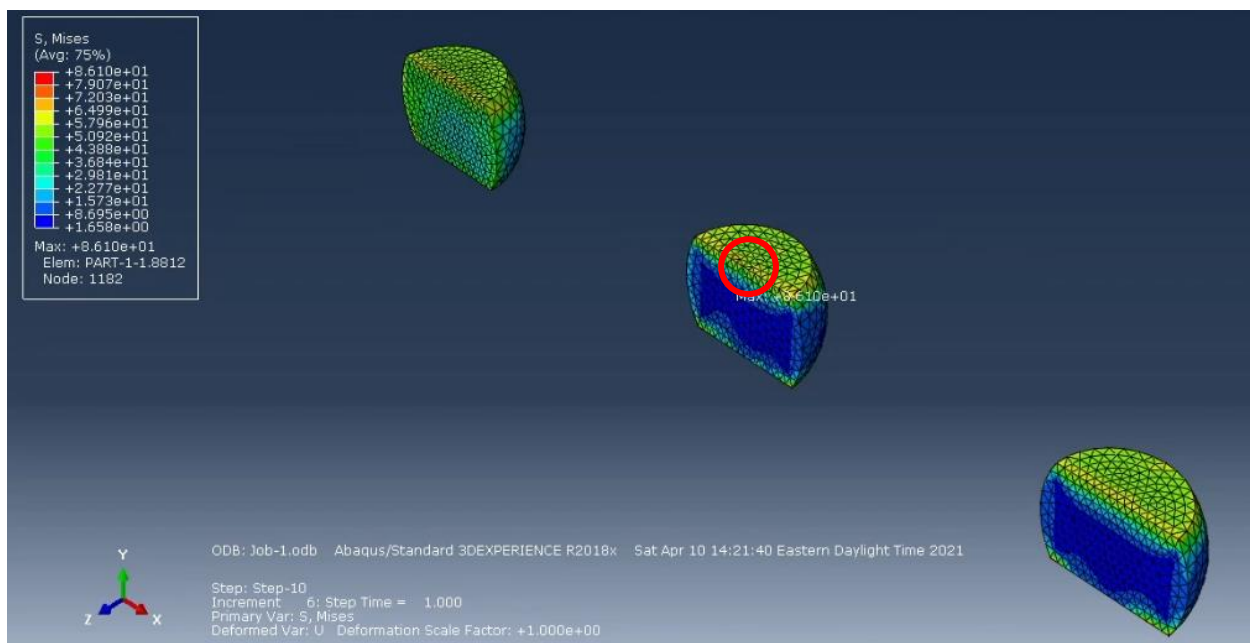


Figure 10 Incompletely Filled Half Model Critical Location (Solder)

Note in Figures 9 and 10, only the Solder is shown and the remaining components have been turned off but were still part of the analysis.

Appendix:

Simulation Run Times:

Completely Filled Quarter Model ~ 52 mins

```
Submitted: Sat Apr 10 18:08:18 2021
Started:  Analysis Input File Processor
Completed: Analysis Input File Processor
Started:  Abaqus/Standard
Completed: Abaqus/Standard
Completed: Sat Apr 10 19:00:56 2021
```

Incompletely Filled Half Model ~ 92 mins

```
Submitted: Sat Apr 10 14:21:01 2021
Started:  Analysis Input File Processor
Completed: Analysis Input File Processor
Started:  Abaqus/Standard
Completed: Abaqus/Standard
Completed: Sat Apr 10 15:53:00 2021
```